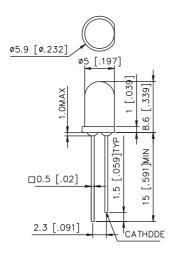
503IRBT



● Chip Material: GaAlAs

Construction: Gas Phase Epitaxial

● Application: Infrared Remote Controller, Optoelectronic Switch

● Lens Color: Blue Transparent

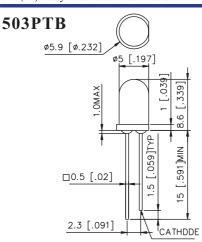
● Absolute Maximum Ranges (Ta=25±3°C)

> 100mW Power Dissipation P_D DC Forward Current ĬΕ 60mA Pulsed Forward Current IFP 160mA *1 Reverse Voltage V_{R} -30~+85°C Operating Temperature Topr Storage Temperature Tstg -40~+85°C Lead soldering Temperature Tsol 260°C for 5 sec

● Electrical and Optical Characteristics (If=20mA, Ta=25±3°C)

Parameter	Symbol	Min,	Тур.	Max.	Test Condition
Radiant Intensity (mW/sr)	Ee	11	13		If=20mA
Peak Wavelength (nm)	λр			950	
Dominant Wavelength (nm)	λd		930		If=20mA
Spectral Bandwidth (nm)	$\triangle \lambda$		50		
Forward Voltage (V)	Vf	1.2	1.35	1.5	
Reverse Current (uA)	Ir			10	$V_R=5V$

(*1) Duty 1/10 Pulse Width 10ms.



- **Chip Material: Silicon**
- Construction: Gas Phase Epitaxial
- Application: Infrared Remote Controller

The device is spectrally matched to infrared emitting diode, e.g. 503IRBT.

- Lens Color: Black Transparent (to filter day light)
- **●** Absolute Maximum Ranges (Ta=25±3°C)

Collector-to-Emitter Breakdown Vo	30V	
Emitter-to-Collector Breakdown Vo	5V	
Power Dissipation	P_D	45mW
Operating Temperature	Topr	-30~+85°C
Storage Temperature	Tstg	-40~+85°C
Lead soldering Temperature	Tsol	260°C for 5 sec

■ Electrical and Optical Characteristics (Ta=25±3°C)

(1 2 0 0)								
Parameter	Symbol	Min.	Typ.	Max.	Test Condition			
Supply Voltage (V)	Vcc	4	4.5	5	DC Voltage			
Supply Current (mA)	Icc			3				
BPF Center Frequency (kHz)	fo		38					
Peak Wavelength (nm)	λр		940					
Reception Distance (m)			8					
Reception Distance (m)			14		At the ray axis			
High Level Pulse Width (μs)	Th	400		800				
Low Level Pulse Width (µs)	Tı	400		800				
High Level Output Voltage (V)	Vh	4.5						
Low Level Output Voltage (V)	Vı		0.2	0.5				

The ray receiving surface at a vertex and relation to the ray axis in the range of 45° and 0° .